

Title (en)
Fabrication methods for thin-well microplate

Title (de)
Herstellungsmethoden für dünnwandige Mikroplatte

Title (fr)
Procédés de fabrication de microplaque à paroi mince

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EP 1316360 A2 20030604 (EN)

Application
EP 03004805 A 20000720

Priority
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Abstract (en)
A thin-well microplate and methods of manufacturing same are provided, wherein the thin-well microplate is conducive for use with automated equipment, and in high temperature procedures. The thin-well microplate is constructed of two components including a skirt and frame portion (11) and a well and deck portion (12) with a plurality of sample wells; both portions being joined to form a unitary microplate. The skirt and frame portion and the well and deck portion are each constructed of the material that will allow each portion to withstand high temperature conditions and use of automated equipment, while retaining the physical characteristics each portion requires for optimal performance of the thin-well microplate. Such physical characteristics include rigidity of the skirt and frame portion and thin-walled sample wells of the well and deck portion to permit optimal thermal transfer and biocompatibility. Methods of construction include forming the thin-well microplate as a unitary plate in a single, two-step process, wherein the skirt and frame portion is constructed of a suitable first material in a first step and the deck and frame portion is formed integral with the skirt and frame portion in a second step of a suitable second material. Another method of construction includes forming the unitary thin-well microplate in two separate manufacturing processes, wherein the skirt and frame portion is constructed of the first material in a first process and the deck and well portion constructed of the second material in a second process, those portions being thereafter, permanently joined by an adhesive system to form the unitary plate. <IMAGE>

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Cited by
EP1872854A1; GB2601137A; US9874501B2; US10545139B2; US7993548B2; WO2006038345A3; WO2013114217A1; WO2008093109A1; WO2007029101A3; WO2011047023A3; US9950323B2; US10792661B2; US8691147B2; US9581527B2; US10725020B2; WO2007028861A1; WO2011101467A1; US11692162B2; US8784752B2; US9557318B2; US9782777B2; US9878328B2; US10632468B2; WO2023057336A1

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